



Kulicke & Soffa to Exhibit at SEMICON China 2019

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SINGAPORE--(BUSINESS WIRE)--Mar. 18, 2019-- Kulicke & Soffa Industries, Inc. (NASDAQ:KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), announced today that it will be exhibiting at the SEMICON China 2019 trade show in Shanghai, China, from March 20 to 22.

The new **ATPremier™ LITE** wafer level bonder will debut at the trade show along with Kulicke & Soffa's latest range of assembly and packaging solutions. The new ATPremier™ LITE wafer bumping system, under the Power Series platform, offers a cost-of-ownership advantage, delivering high productivity with increased efficiency. The system is also compatible with an Automatic Wafer Handler system to enable factory automation.

Other recently introduced, K&S's solution such as the **RAPID™ MEMGEN-Sseries** ball bonder, **Asterion™** hybrid wedge bonder and high performance **PowerFusion™ TL** wedge bonder will also be showcased. A system-in-a-package (SiP) line featuring the K&S **iFlex T2** PoP equipment along with a screen printer and an automatic optical inspection system, will demonstrate a full solution for package-on-package interconnect. The Company will also be demonstrating the capability of its **KNet PLUS** connectivity software designed to connect all K&S equipment and other SECS-II/GEM compliant equipment.

Nelson Wong, Kulicke & Soffa's Senior Vice President of Ball Bonder Business Unit, said, "With the rise of smart automation and connected systems in the age of Industry 4.0, K&S continues to invest in R&D to develop solutions which offer connectivity, intelligence and flexible automation to help our customers enhance efficiency and to improve productivity and reliability."

Customers can see the full assembly of solutions at the SEMICON China trade show in Shanghai, China, Hall N3, Booth #3411.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ:KLIC) is a leading provider of semiconductor packaging and electronic assembly solutions supporting the global automotive, consumer, communications, computing and industrial segments. As a pioneer in the semiconductor space, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, electronics assembly, wedge bonding and a broader range of expendable tools to its core offerings. Combined with its extensive expertise in process technology and focus on development, K&S is well positioned to help customers meet the challenges of packaging and assembling the next-generation of electronic devices. (www.kns.com)

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